

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-213777

(43)Date of publication of application : 15.08.1997

(51)Int.CI.

H01L 21/68  
H02N 13/00

(21)Application number : 08-015469

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(22)Date of filing : 31.01.1996

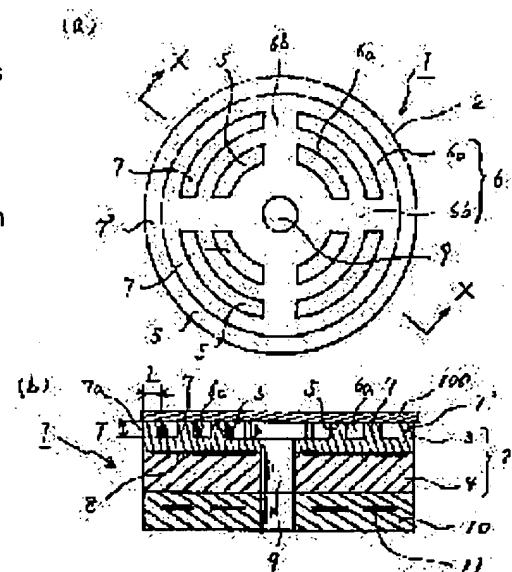
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## (54) ELECTROSTATIC CHUCK

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To reduce the amount of adhesion of foreign matter to a semiconductor wafer, and also, heat a semiconductor wafer equally without leaking gas such as He, etc., supplied to the groove of a holding face into a chamber, in an electrostatic chuck where a groove is made on the surface of a dielectric layer.

**SOLUTION:** In an electrostatic chuck which is equipped with an electrostatic electrode 8 on one surface of the dielectric layer 3 consisting of ceramic or sapphire, and also has a groove 6 made on the other surface thereby being made uneven, and in which the apex of the projection 7 serves as a holding face, at least the width of the projection at the outermost periphery is made 1-20mm out of the projections 7 constituting the holding face, and besides the apex is made a smooth face 0.3 or under in average roughness (Ra) of center line. Moreover, the depth of the groove 6 provided at the above holding face is made 5μm or over.



## LEGAL STATUS

[Date of request for examination] 11.11.1999

[Date of sending the examiner's decision of rejection] 22.10.2002

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's  
decision of rejection]

[Date of extinction of right]

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